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FILE COVERS 1907 - 29 May 2003 VOL 138 ISS 23

FILE LAST UPDATED: 29 May 2003 (20030529/ED)

This file contains CAS Registry Numbers for easy and accurate substance identification.

=> E JP08029980/PN

E1	2	JP08029979/PN
E2	1	JP08029979 B/PN
E3	2 -->	JP08029980/PN
E4	1	JP08029980 B/PN
E5	2	JP08029981/PN
E6	1	JP08029981 B/PN
E7	2	JP08029982/PN
E8	1	JP08029982 B/PN
E9	2	JP08029983/PN
E10	1	JP08029983 B/PN
E11	2	JP08029984/PN
E12	1	JP08029984 B/PN

=> S E3-4

	2	JP08029980/PN
	1	"JP08029980 B"/PN
		(JP08029980 B#/PN)
L1	2	(JP08029980/PN OR "JP08029980 B"/PN)

=> D ALL

L1 ANSWER 1 OF 2 CA COPYRIGHT 2003 ACS
AN 124:356233 CA
TI Alkali-developable photoresist composition for preparing circuit boards
IN Shioda, Atsushi; Hashimoto, Kazumi; Chiba, Hideki
PA Japan Synthetic Rubber Co Ltd, Japan
SO Jpn. Kokai Tokkyo Koho, 16 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
IC ICM G03F007-038
ICS G03F007-027; G03F007-028; G03F007-032; H05K003-06; H05K003-18;
H05K003-28

CC 74-5 (Radiation Chemistry, Photochemistry, and Photographic and Other Reprographic Processes)

Section cross-reference(s): 76

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 08029980	A2	19960202	JP 1994-185346	19940714 <--
PRAI	JP 1994-185346		19940714		
AB	The title photoresist compn. contains (a) an unsatd. group-contg. polycarboxylic acid resin prepd. by reaction of a copolymer of unsatd. carboxylic acids and other radically polymg. compds. with an epoxy group-contg. radically polymg. compd., (b) a polymg. compd. having .gtoreq.1 ethylenic unsatd. double bond, and (c) a photopolymn. initiator. The compn. shows good alkali-developability, high resoln. even if its film is thick, and improved resistance to plating, chems., and soft solder. Thus, a photoresist compn. comprised a resin prepd. by reaction of methacrylic acid-dicyclopentanyl methacrylate-butadiene copolymer with glycidyl methacrylate, Aronix M-8060 (monomer), and Irgacure 369 (photopolymn. initiator).				
ST	polycarboxylic acid resin photoresist; circuit board photoresist compn				
IT	Resists (photo-, alkali-developable photoresist compn. contg. unsatd. polycarboxylic acid resin)				
IT	177017-77-5P	177017-78-6P	177017-79-7P	177017-80-0P	177017-81-1P
	177017-82-2P	177017-83-3P	177017-84-4P	177017-85-5P	
	RL: PNU (Preparation, unclassified); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses) (alkali-developable photoresist compn. contg. unsatd. polycarboxylic acid resin)				
IT	15625-89-5, Kayarad TMPTA	62886-89-9, Aronix M 8060	64401-02-1		
	93294-97-4, Kayarad DPCA 60				
	RL: TEM (Technical or engineered material use); USES (Uses) (alkali-developable photoresist compn. contg. unsatd. polycarboxylic acid resin)				

=> D ALL 2

L1 ANSWER 2 OF 2 CA COPYRIGHT 2003 ACS
AN 108:178503 CA
TI Dielectric ceramics
IN Yokoya, Yoichiro; Kato, Junichi; Mihara, Toshihiro
PA Matsushita Electric Industrial Co., Ltd., Japan
SO Jpn. Kokai Tokkyo Koho, 4 pp.
CODEN: JKXXAF

DT Patent
LA Japanese
IC ICM C04B035-46
ICS C04B035-00; H01B003-12
ICA H01G004-12
CC 76-10 (Electric Phenomena)
Section cross-reference(s): 57

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 62123063	A2	19870604	JP 1985-264064	19851125 <--
	JP 08029980	B4	19960327		
PRAI	JP 1985-264064		19851125		
AB	The title ceramics are described by the general formula (PbaMb) (Mg1/2W1/2)xTiyO2+a+b (M = Ca, Sr, and/or Ba; 1.001 .ltoreq. a + b .ltoreq.1.250; 0.001 .ltoreq. b .ltoreq.0.225; 0.200 .ltoreq. x .ltoreq.0.700; x + y = 1.00). The ceramics, which are prepd. at relatively low sintering temps., have high resistivities and high densities, and are useful for laminated capacitors. PbO, MgO, TiO2,				

SrCO₃, and WO₃ were wet-mixed, presintered, pulverized, molded, and sintered at 960.degree. in a N₂-H₂ atm. (O₂ partial pressure 1.0 .times. 10⁻⁸ atm) to obtain a ceramic having suitable properties for use in laminated capacitors.

ST laminated capacitor dielec ceramic; alk earth lead multimetal oxide dielec; calcium lead magnesium tungstate titanate dielec; strontium lead magnesium tungstate titanate dielec; barium lead magnesium tungstate titanate dielec

IT Electric insulators and Dielectrics

(ceramic, for laminated capacitors, low-temp. sinterable)

IT 107762-63-0 114104-26-6 114104-27-7 114104-28-8 114104-29-9

114104-30-2 114104-31-3 114104-32-4 114104-33-5 114104-34-6

114104-35-7 114104-36-8 114104-37-9 114135-39-6

RL: TEM (Technical or engineered material use); USES (Uses)

(dielec. ceramic, for laminated capacitors)

IT 7440-24-6, uses and miscellaneous 7440-39-3, uses and miscellaneous

7440-70-2, uses and miscellaneous

RL: USES (Uses)

(dielec. ceramics based on lead magnesium tungstate titanate contg.)

IT 107762-63-0

RL: TEM (Technical or engineered material use); USES (Uses)

(dielec. ceramics from strontium-contg. or barium-contg., for laminated capacitors)

=> E JP08160616/PN

E1 1 JP08160614/PN

E2 1 JP08160615/PN

E3 1 --> JP08160616/PN

E4 1 JP08160617/PN

E5 1 JP08160618/PN

E6 1 JP08160619/PN

E7 1 JP08160620/PN

E8 1 JP08160621/PN

E9 1 JP08160622/PN

E10 1 JP08160623/PN

E11 1 JP08160624/PN

E12 1 JP08160625/PN

=> S E3;D ALL

L2 1 JP08160616/PN

L2 ANSWER 1 OF 1 CA COPYRIGHT 2003 ACS

AN 125:208436 CA

TI Manufacture of resist polymer composition and photosolder resist

IN Okazaki, Eiichi; Nitsuta, Masao; Nakagawa, Sumie; Oota, Hiroyuki

PA Toa Gosei Kk, Japan

SO Jpn. Kokai Tokkyo Koho, 10 pp.

CODEN: JKXXAF

DT Patent

LA Japanese

IC ICM G03F007-027

ICS C08F299-00; C08G059-14; C08G059-17; C08G059-40; H05K003-28

CC 74-5 (Radiation Chemistry, Photochemistry, and Photographic and Other Reprographic Processes)

Section cross-reference(s): 38

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 08160616	A2	19960621	JP 1994-332122	19941212 <--
PRAI	JP 1994-332122		19941212		

AB The compn. is manufd. by treating (A) a copolymer of a (meth)acrylate

contg. one epoxy group and .gtoreq.1 monomer contg. one ethylenically unsatd. group and (B) a monomer contg. .gtoreq.1 ethylenically unsatd. group and one CO₂H and then treating the OH group of the reaction product with (C) a divalent carboxylic anhydride. The photosolder resist is obtained from the compn. The resist is useful for manuf. of printed circuit boards, metalworking, etc. The resist gave a film with good chem., heat, and solvent resistance.

ST epoxy acrylate polymer photosolder resist; alkali developable resist epoxy acrylate

IT Epoxy resins, uses

RL: POF (Polymer in formulation); TEM (Technical or engineered material use); USES (Uses)

(acrylic, manuf. of resist polymer compn. and alkali-developable photosolder resist)

IT Acrylic polymers, uses

RL: POF (Polymer in formulation); TEM (Technical or engineered material use); USES (Uses)

(epoxy, manuf. of resist polymer compn. and alkali-developable photosolder resist)

IT Resists

(photo-, manuf. of resist polymer compn. and alkali-developable photosolder resist)

IT 180980-02-3P 180980-03-4P 180980-06-7P 180980-08-9P 180980-09-0P

RL: IMF (Industrial manufacture); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)

(manuf. of resist polymer compn. and alkali-developable photosolder resist)

IT 28825-96-9, TEPIC 29570-58-9, Aronix M 400

RL: TEM (Technical or engineered material use); USES (Uses)

(manuf. of resist polymer compn. and alkali-developable photosolder resist)